

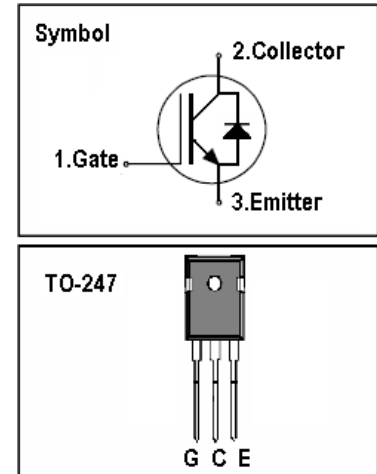
IGBT

Features

- 1200V,15A
- $V_{CE(sat)(typ.)}=1.9V@V_{GE}=15V,I_C=15A$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

General Description

JIAEN FS-IGBTs offer lower losses and higher energy efficiency for application such as IH (induction heating),UPS, general inverter and other soft switching applications.



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 30	V
I_C	Continuous Collector Current ($T_C=25^\circ C$)	30	A
	Continuous Collector Current ($T_C=100^\circ C$)	15	A
I_{CM}	Pulsed Collector Current (Note 1)	45	A
I_F	Diode Continuous Forward Current ($T_C=100^\circ C$)	15	A
I_{FM}	Diode Maximum Forward Current (Note 1)	45	A
t_{sc}	Short Circuit Withstand Time	10	us
P_D	Maximum Power Dissipation ($T_C=25^\circ C$)	105	W
	Maximum Power Dissipation ($T_C=100^\circ C$)	40	W
T_J	Operating Junction Temperature Range	-55 to +175	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{th\ j-c}$	Thermal Resistance, Junction to case for IGBT	1.15	$^\circ C/W$
$R_{th\ j-c}$	Thermal Resistance, Junction to case for Diode	1.5	$^\circ C/W$
$R_{th\ j-a}$	Thermal Resistance, Junction to Ambient	40	$^\circ C/W$

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units	
BV_{CES}	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	1200	-	-	V	
I_{CES}	Collector-Emitter Leakage Current	$V_{CE}=1200V, V_{GE}=0V$	-	-	100	μA	
I_{GES}	Gate Leakage Current, Forward	$V_{GE}=30V, V_{CE}=0V$	-	-	100	nA	
	Gate Leakage Current, Reverse	$V_{GE}=-30V, V_{CE}=0V$	-	-	100	nA	
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	4.5	-	6.5	V	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=15A$	-	1.9	-	V	
Q_g	Total Gate Charge	$V_{CC}=960V$ $V_{GE}=15V$ $I_C=15A$	-	68	-	nC	
Q_{ge}	Gate-Emitter Charge		-	20.4	-	nC	
Q_{gc}	Gate-Collector Charge		-	37.6	-	nC	
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V$ $V_{GE}=15V$ $I_C=15A$ $R_G=15\Omega$ Inductive Load $T_C=25^\circ\text{C}$	-	20	-	ns	
t_r	Turn-on Rise Time		-	38	-	ns	
$t_{d(off)}$	Turn-off Delay Time		-	126	-	ns	
t_f	Turn-off Fall Time		-	174	-	ns	
E_{on}	Turn-on Switching Loss		-	0.45	-	mJ	
E_{off}	Turn-off Switching Loss		-	0.70	-	mJ	
E_{ts}	Total Switching Loss		-	1.15	-	mJ	
$t_{d(on)}$	Turn-on Delay Time		$V_{CC}=600V$ $V_{GE}=15V$ $I_C=15A$ $R_G=15\Omega$ Inductive Load $T_C=175^\circ\text{C}$	-	22	-	ns
t_r	Turn-on Rise Time			-	38	-	ns
$t_{d(off)}$	Turn-off Delay Time			-	168	-	ns
t_f	Turn-off Fall Time	-		302	-	ns	
E_{on}	Turn-on Switching Loss	-		0.55	-	mJ	
E_{off}	Turn-off Switching Loss	-		1.15	-	mJ	
E_{ts}	Total Switching Loss	-		1.7	-	mJ	
C_{ies}	Input Capacitance	$V_{CE}=25V$ $V_{GE}=0V$ $f=1\text{MHz}$	-	1425	-	pF	
C_{oes}	Output Capacitance		-	78	-	pF	
C_{res}	Reverse Transfer Capacitance		-	30	-	pF	

Electrical Characteristics of Diode ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=15A$	-	1.9	2.6	V
t_{rr}	Diode Reverse Recovery Time	$V_{CE}=600V$ $I_F=15A$	-	230	-	ns
I_{rr}	Diode peak Reverse Recovery Current		-	27	-	A
Q_{rr}	Diode Reverse Recovery Charge	$dI_F/dt=200A/\mu s$	-	1260	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature

Typical Performance Characteristics

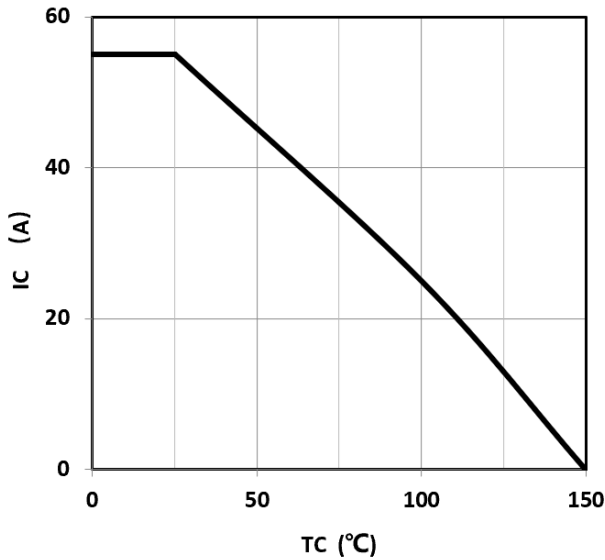


Figure1:maximum DC collector current VS. case temprature

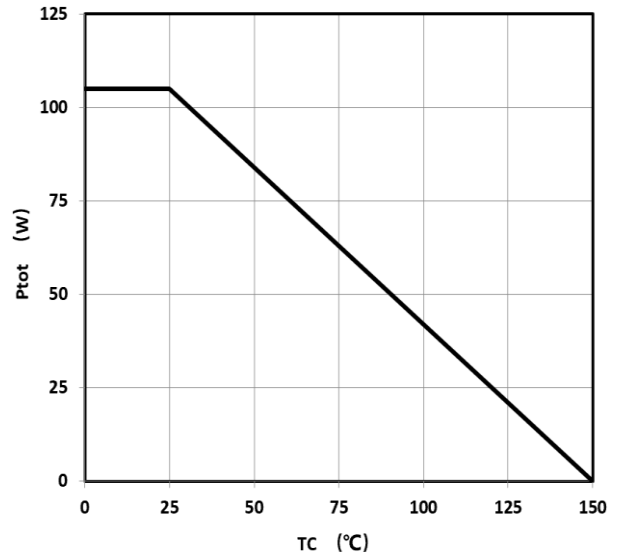


Figure2:power dissipation VS. case temprature

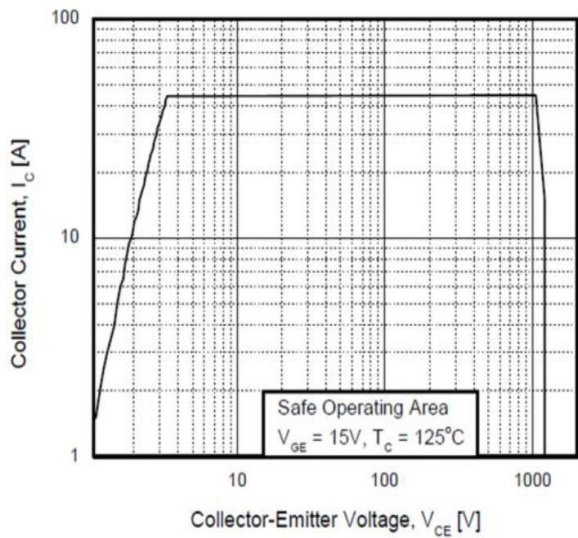


Figure3:reverse bias SOA, $T_J=125^\circ C, V_{GE}=15V$

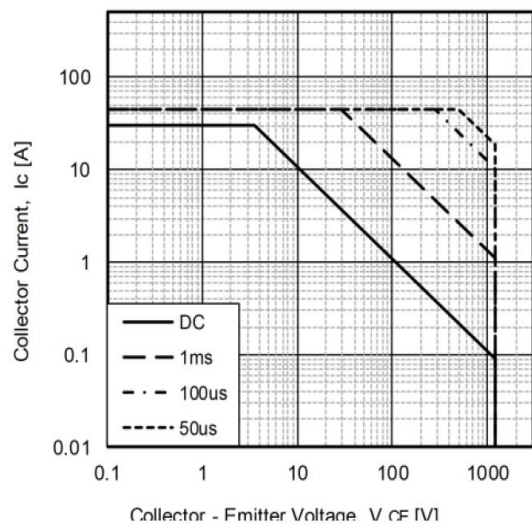


Figure4:forward SOA, $T_C=25^\circ C, T_J \le 150^\circ C$

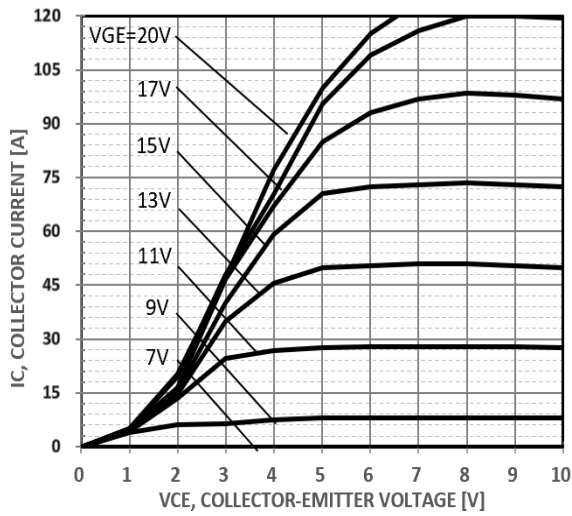


Figure5:typical IGBT output characteristics,
 $T_J=25^{\circ}\text{C}; t_p=300\mu\text{s}$

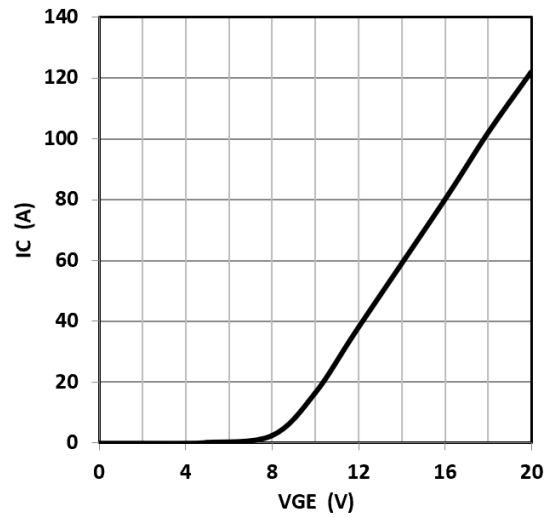


Figure6:typical trans characteristics,
 $V_{CE}=20\text{V}, t_p=20\mu\text{s}$

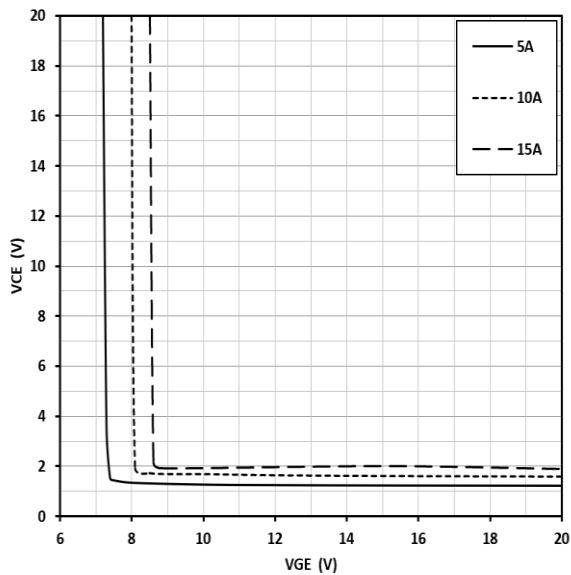


Figure7: typical VCE VS. VGE, $T_J=25^{\circ}\text{C}$

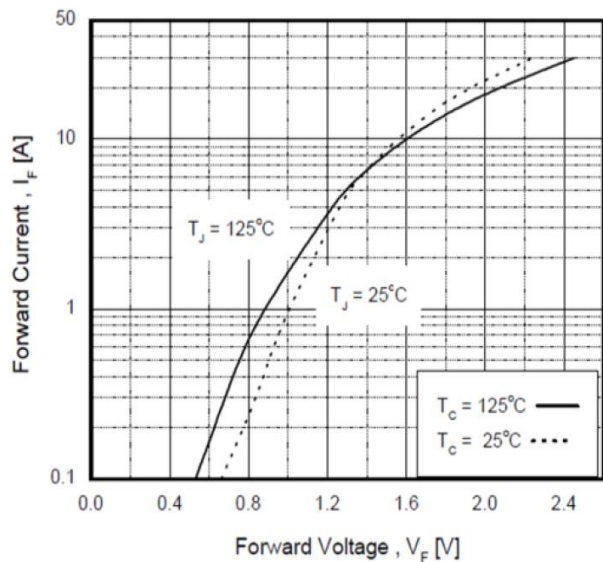


Figure8:typical diode forward characteristic, $t_p=300\mu\text{s}$

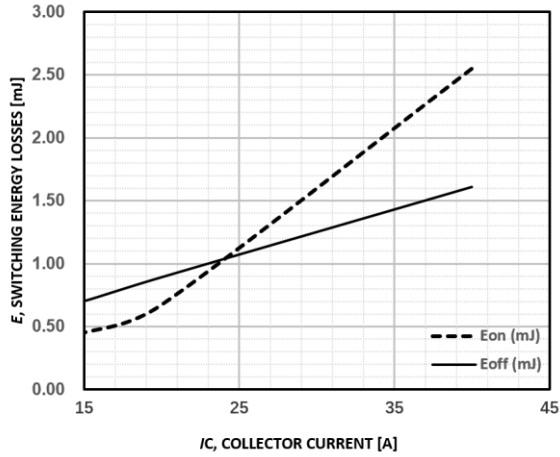


Figure9: typical energy loss VS. IC, TC=25°C,
L=500uH , VCE=600V,VGE=15V,Rg=15Ω

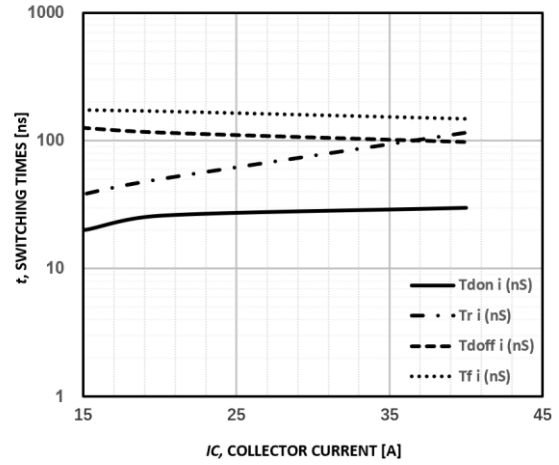


Figure10: typical switching time VS. IC, TC=25°C,
L=500uH, VCE=600V,VGE=15V,Rg=15Ω

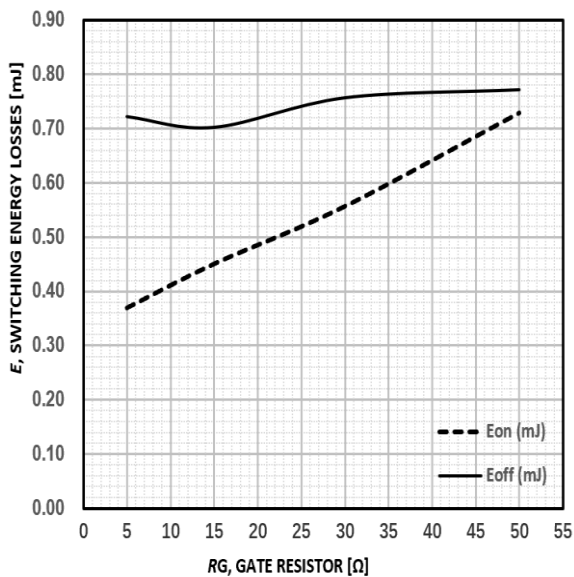


Figure11: typical energy loss VS. Rg,TC=25°C,
L=500uH, VCE=600V, VGE=15V ,IC=15A

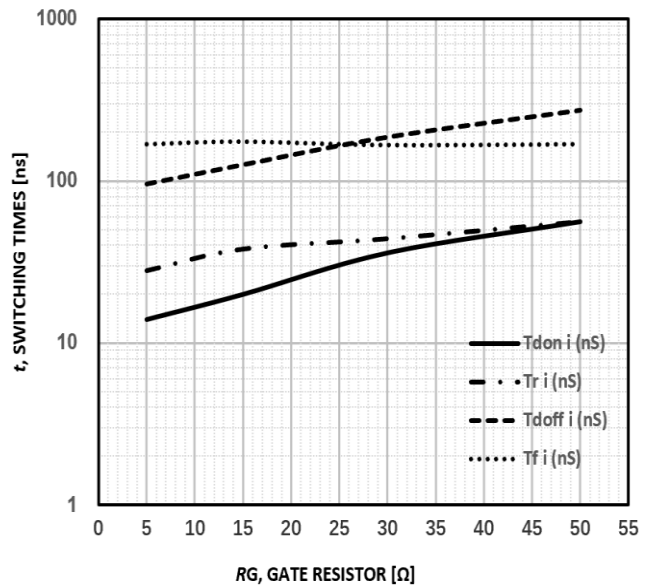


Figure12: typical switching time VS. Rg,TC=25°C,
L=500uH,VCE=600V,VGE=15V,IC=15A

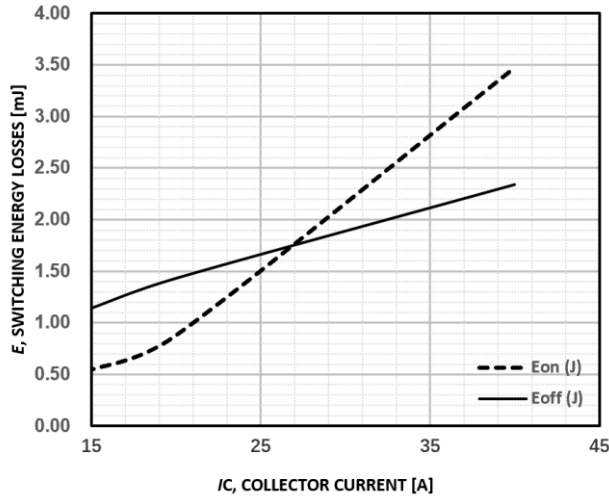


Figure13: typical energy loss VS. IC, TC=175°C,

L=500uH , VCE=600V, VGE=15V, Rg=15Ω

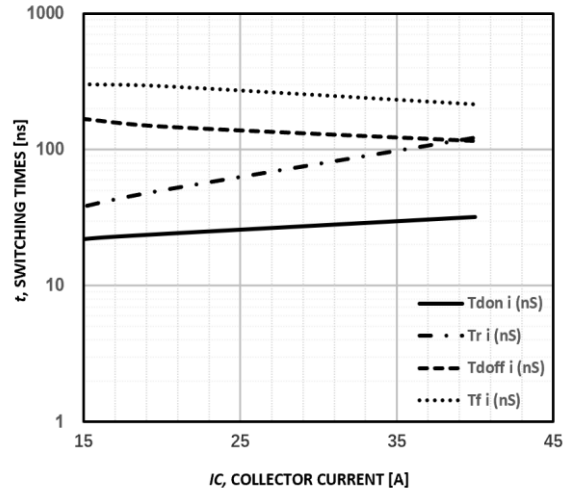


Figure14: typical switching time VS. IC, TC=175°C,

L=500uH, VCE=600V, VGE=15V, Rg=15Ω

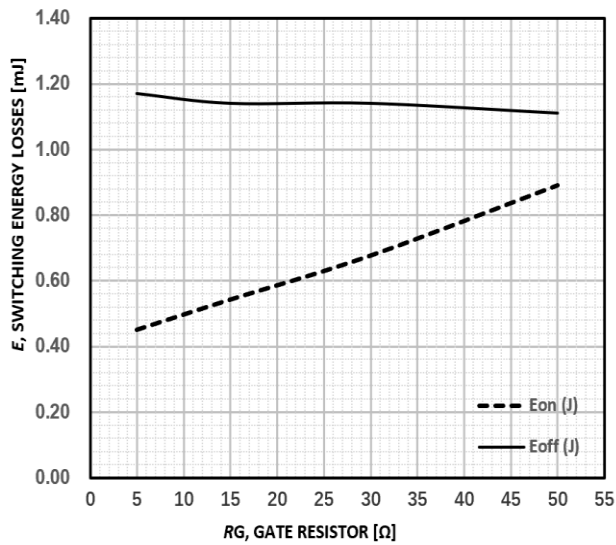


Figure15: typical energy loss VS. Rg, TC=175°C,

L=500uH, VCE=600V, VGE=15V, IC=15A

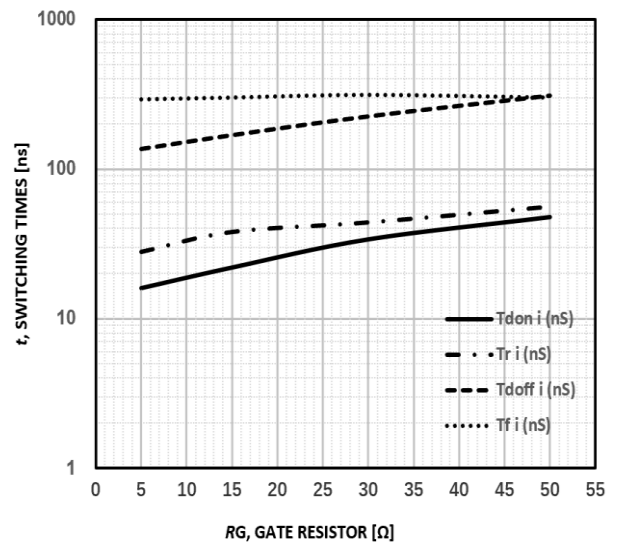


Figure16: typical switching time VS. Rg, TC=175°C,

L=500uH, VCE=600V, VGE=15V, IC=15A

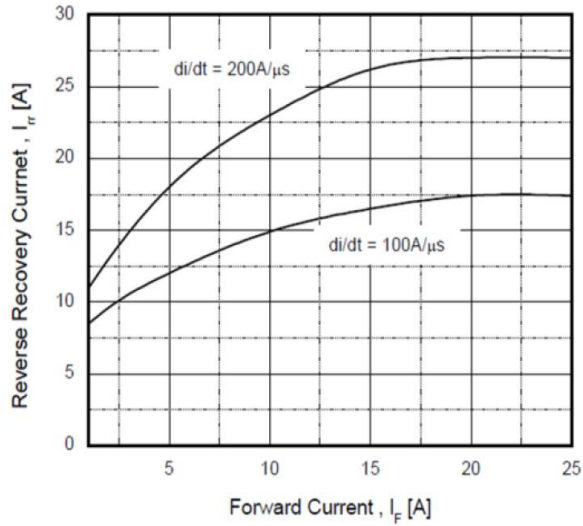


Figure17: typical diode IRR VS. IF, TC=25°C

VCC=600V, VGE=15V

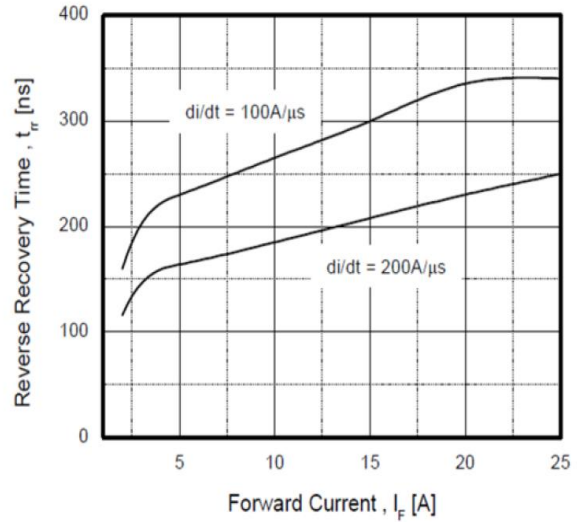


Figure18: Reverse Recovery Time

VCC=600V, VGE=15V

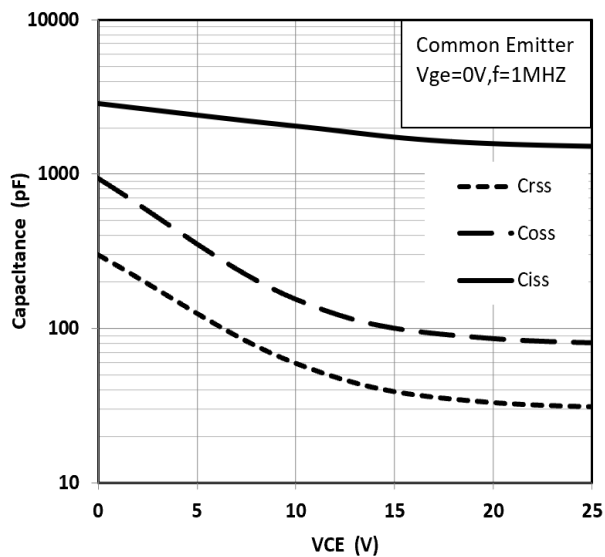


Figure19: typical capacitance VS. VCE,

VGE=0V, f=100kHz

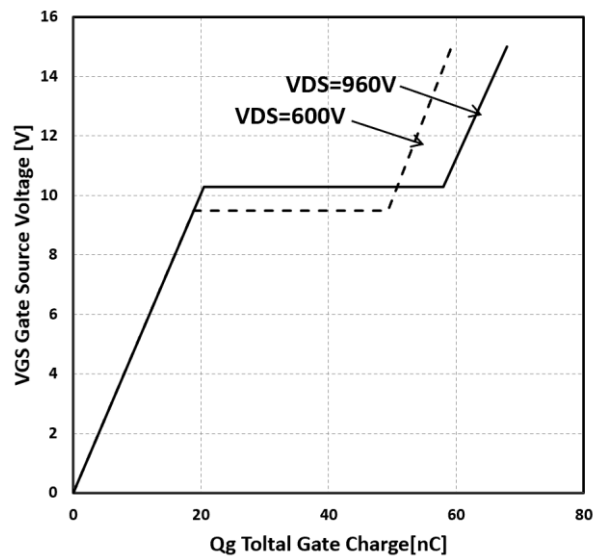


Figure20: typical gate charge VS. VGE, IC=15A

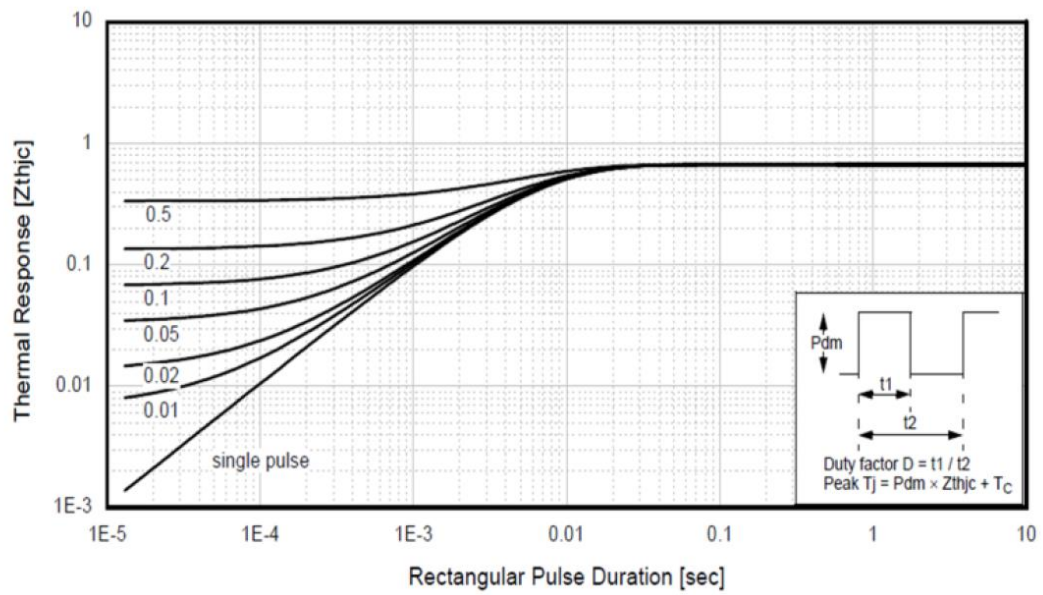
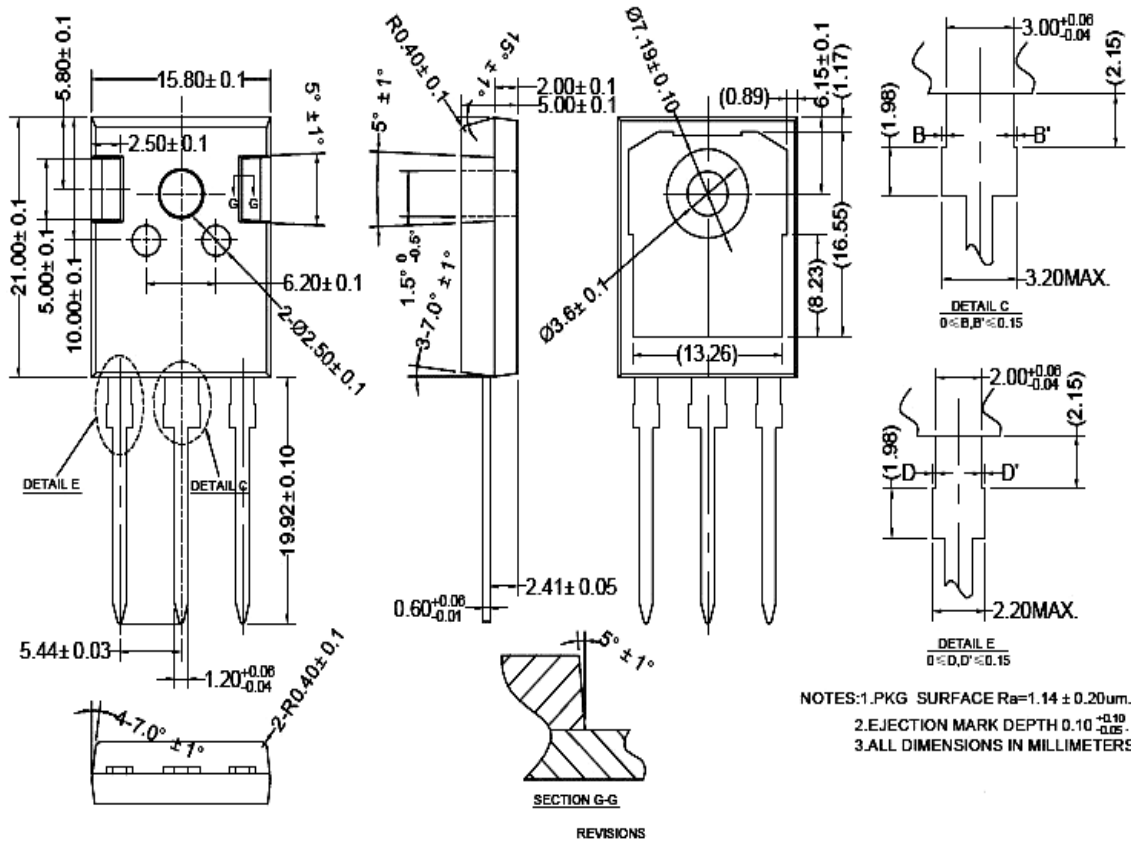


Figure21: normalized transient thermal impedance, junction-to-case

Note1. Duty factor $D = t1 / t2$ Note2: peak TJ = PDM × Zthjc + TC

TO247 PACKAGE OUTLINE



公差标注	公差值	表面粗糙度
0	±0.2	Ra3.2~6.3
0.0	±0.1	Ra1.6~3.2
0.00	±0.01	Ra0.8~1.6
0.000	±0.005	Ra0.4~0.8
0.0000	±0.002	Ra0.2~0.4

0 ≤ D, D' ≤ 0.15

NOTES: 1. PKG SURFACE Ra=1.14 ± 0.20um.
2. EJECTION MARK DEPTH 0.10 ^{+0.10}/_{-0.05}.
3. ALL DIMENSIONS IN MILLIMETERS.

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